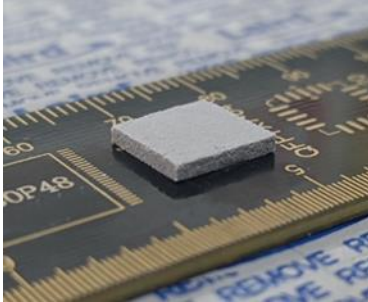


PRODUCT DESCRIPTION



Laird's Tflex™ HD7.5 gap filler is a new developed very soft silicone material in our high deflection series. With a thermal conductivity of 7.5W/ mk, Tflex™ HD7.5 is designed to provide superior pressure versus deflection characteristics. The material will provide minimal stress on components during application while maintaining low thermal resistance. As a result, less mechanical and thermal stresses will be experienced within your device.

Tflex™ HD7.5 gap filler is available in thickness from 1mm (0.040") to 5mm (0.200"). Laird can provide material to meet your production needs in any region through our local production facilities. Please contact your local Laird sales or field engineering contact for samples or questions.

FEATURES AND BENEFITS

- 7.5 W/mK thermal conductivity
- Low pressure versus deflection
- Minimizes board and component stress
- Low Outgassing and oil bleeding
- Large tolerance applications

SPECIFICATIONS

TYPICAL PROPERTIES	VALUE	TEST METHOD
Construction & Composition	Ceramic filled silicone sheet	N/A
Color	Grey	Visual
Thickness Range	1mm (0.040") - 5mm (0.200")	N/A
Thermal Conductivity (W/mK)	7.5 6.8	Hot Disk ASTMD5470
Density (g/cc)	3.4	Helium Pycnometer
Hardness Shore 00 (3 sec)	15	ASTM D2240
Hardness Shore 000 (3 sec)	60	ASTM D2240
Outgassing TML (weight %)	0.20	ASTM E595
Outgassing CVCM (weight %)	0.02	ASTM E595
Temperature Range	-40°C to 125°C	Laird Test Method
Rth at 1mm, 10 psi	0.119°C-in ² /W	ASTM D5470
Dielectric Constant at 1 MHz	7.94	ASTM D150
UL Flammability Rating	V-0	UL 94
Volume Resistivity	1.1X10 ¹⁴ Ω.cm	ASTM D257

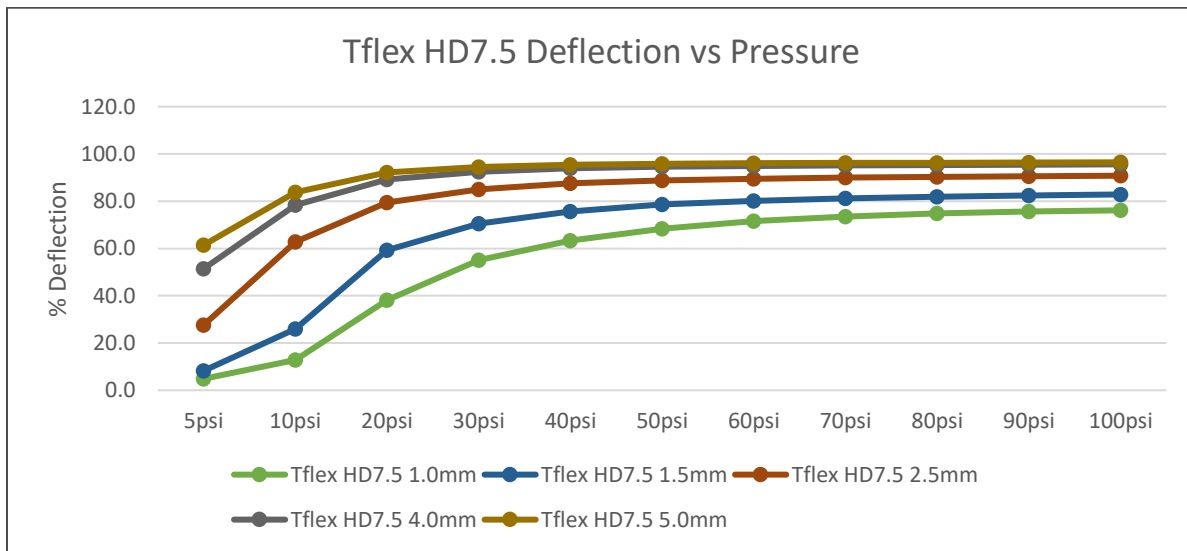
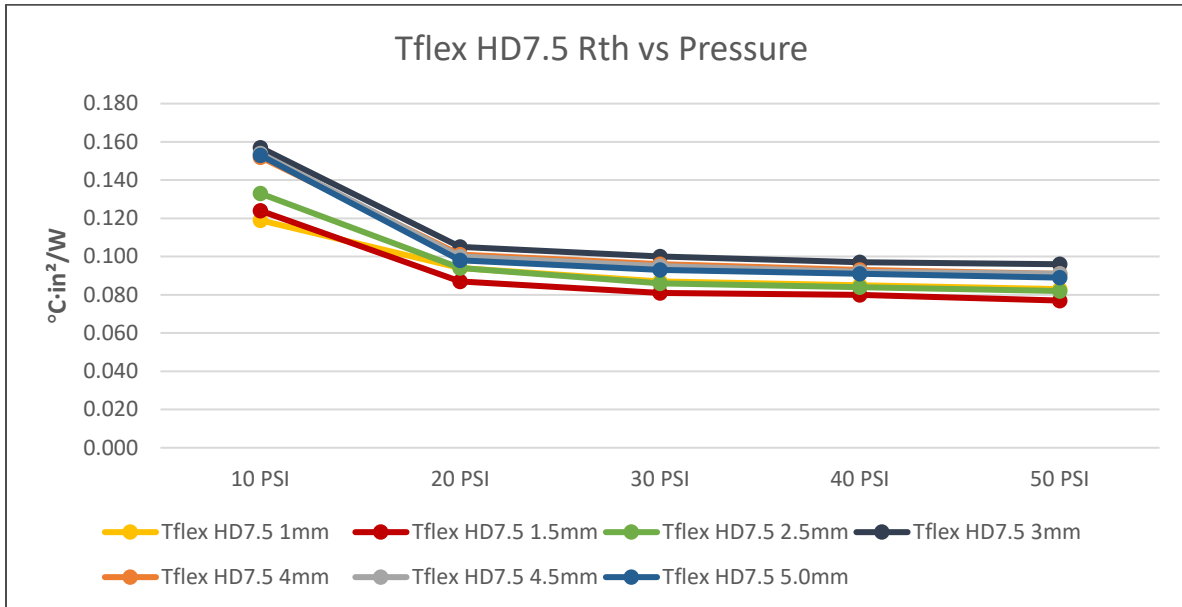
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THR-DS-Tflex™ HD7.5 06122023

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AVAILABILITY

- 1 mm (0.040”) up to 5 mm (0.200”) thick material available in 0.25mm (0.010”) increments
- Available in standard sheet sizes of 18” x 18” and 9” x 9” or custom die cut parts.
- DC1 – Eliminate tack from one side
- A1 – Adhesive on one side
- PI – Polyimide liner added to one side

PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. HD7.5 indicates high deflection 7.5 W/mk material. Thickness of sheet in mm is listed after material name.

EXAMPLES:

- Tflex™ HD7.5,1.00 =1.00mm thick for Tflex™ HD7.5 material
- Tflex™ HD7.5,1.00,A1 =1.00mm thick for Tflex™ HD7.5 material with adhesive on one side

Tflex™ HD7.5 datasheet 06122023

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